



# Product Change Notification

**Change Notification #:** 815041-00

**Change Title:** Intel® Data Center GPU Flex 170,  
PCN 815041-00, Transport Media,  
AIC Packaging Update

**Date of Publication:** February 07, 2024

## Key Characteristics of the Change:

Transport Media

## Forecasted Key Milestones:

<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	March 15, 2024
<b>Date of First Availability of Post-Conversion Material:</b>	March 12, 2024

## Description of Change to the Customer:

The Intel SKUs listed in the products affected table will have the following changes.

1. The AIC (Add In Card) packaging is changing from “2-Pack” (two AICs in each box) to “1-Pack” (one AIC in each box) for the Flex 170 product. Inventory will transition in the Intel factory on or beyond the above date to replace the previous packaging.

2. Packaging change details.

	Previous Packaging	New Packaging
Description	2-Pack	1-Pack
Flex 170 (MMID 99AK03) Packaging Part #	PKGKIT M56784-001	PKGKIT M92270-001

**Previous Flex 170 Packaging 2-Pack**



**New Flex 170 Packaging 1-Pack**



## Customer Impact of Change and Recommended Action:

The packaging change offers increased order fulfillment flexibility, and Intel anticipates no product impact with this change.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material. Customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

## Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Data Center GPU Flex 170	24P01G00BA	99AK03

## PCN Revision History:

**Date of Revision:**

February 07, 2024

**Revision Number:**

00

**Reason:**

Originally Published PCN



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No response from customers will be deemed an acceptance of the change, and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below.

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